



### P-Channel Enhancement-Mode MOSFET (-30V, -4.3A)

PRODUCT SUMMARY		
V <sub>DSS</sub>	I <sub>D</sub>	R <sub>DS(on)</sub> (mΩ) Max
-30V	-4.3A	60 @ V <sub>GS</sub> = -10 V, I <sub>D</sub> =-4.3A
		78 @ V <sub>GS</sub> = -4.5V, I <sub>D</sub> =-3.0A

### Features

- Super high dense cell trench design for low R<sub>DS(on)</sub>.
- Rugged and reliable.
- SOT-23-3L package
- Ordering information: GV3407-G (Lead(Pb)-free and halogen-free)

RoHS+HF

	GV3407 Pin Assignment & Symbol  3-Lead Plastic <b>SOT-23-3L</b> Pin 1: Gate 2: Source 3: Drain	
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### Absolute Maximum Ratings (T<sub>A</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Ratings	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current @ T <sub>A</sub> =25°C	-4.3	A
I <sub>DM</sub>	Drain Current (Pulsed) <sup>a</sup>	-20	A
I <sub>S</sub>	Maximum Body-Diode Continuous Current	-2	A
P <sub>D</sub>	Total Power Dissipation @ T <sub>A</sub> =25°C	1.4	W
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>j</sub>	Junction Temperature	150	°C
R <sub>θJA</sub>	Thermal Resistance Junction to Ambient (PCB mounted) <sup>b</sup>	125	°C/W

Note: a: Pulse width limited by the maximum junction temperature

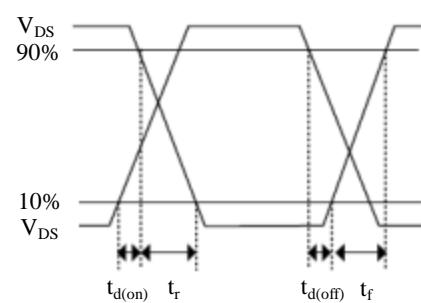
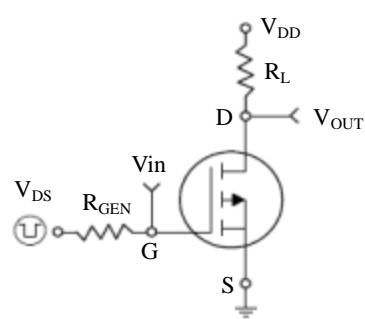
b: 1-in<sup>2</sup> 2oz Cu PCB board

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
<b>• Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>• On Characteristics<sup>c</sup></b>						
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-	-2.5	V
$I_{\text{DS(on)}}$	On state drain current	$V_{\text{DS}}=-5\text{V}, V_{\text{GS}}=-10\text{V}$	-30	-	-	A
$R_{\text{DS(on)}}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-4.3\text{A}$	-	55	60	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-3.0\text{A}$	-	65	78	
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-4.3\text{A}$	-	11	-	S
<b>• Dynamic Characteristics<sup>d</sup></b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	668	-	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		-	126	-	
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	92	-	
$R_g$	Gate resistance	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	6	-	$\Omega$
<b>• Switching Characteristics<sup>d</sup></b>						
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-4.3\text{A}, V_{\text{GS}}=-10\text{V}$	-	12.7	-	$\text{nC}$
$Q_g$	Total Gate Charge (4.5V)		-	6.4	-	
$Q_{\text{gs}}$	Gate-Source Charge		-	2	-	
$Q_{\text{gd}}$	Gate-Drain Charge		-	4	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=-10\text{V}, R_{\text{L}}=3.5\Omega, R_{\text{GEN}}=3\Omega$	-	7.7	-	$\text{nS}$
$t_r$	Turn-on Rise Time		-	6.8	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	20	-	
$t_f$	Turn-off Fall Time		-	10	-	
<b>• Drain-Source Diode Characteristics</b>						
$V_{\text{SD}}$	Drain-Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-1.0\text{A}$	-	-	-1	V

Note: c: Pulse Test : Pulse Width < 300μs, Duty Cycle < 2%

d: Guaranteed by design, not subject to production testing.



### Characteristics Curve

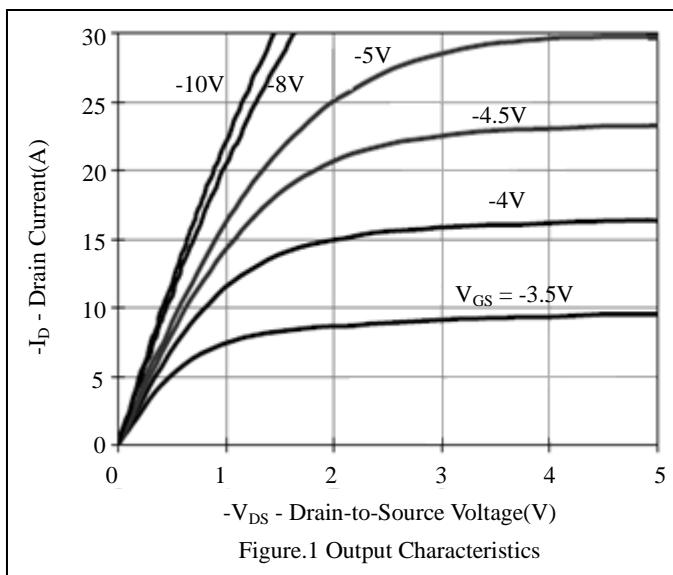


Figure.1 Output Characteristics

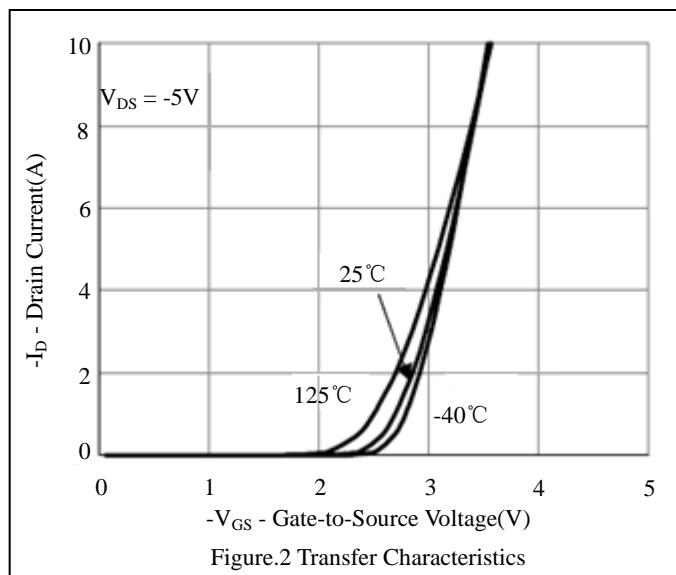


Figure.2 Transfer Characteristics

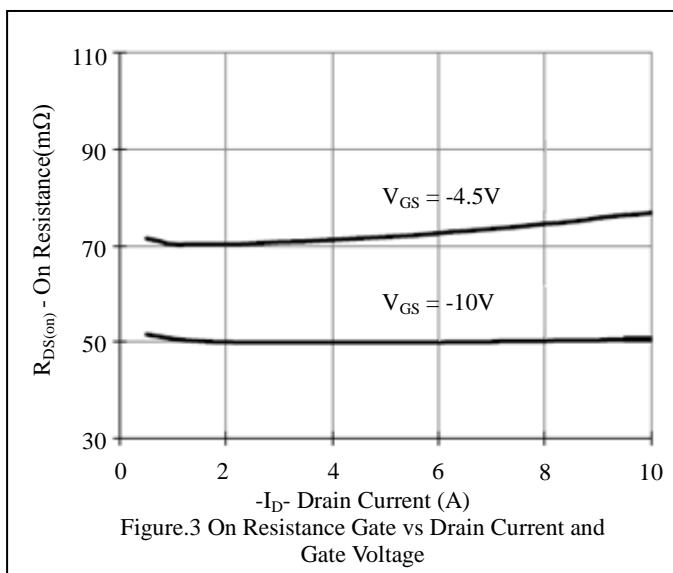


Figure.3 On Resistance Gate vs Drain Current and Gate Voltage

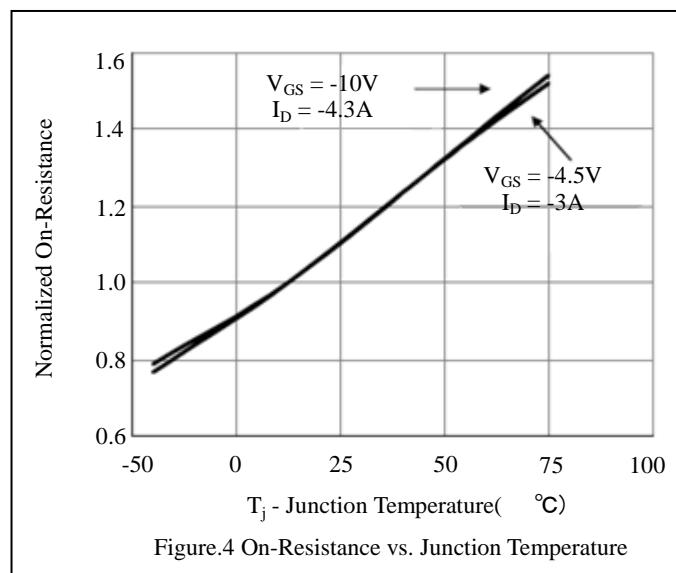


Figure.4 On-Resistance vs. Junction Temperature

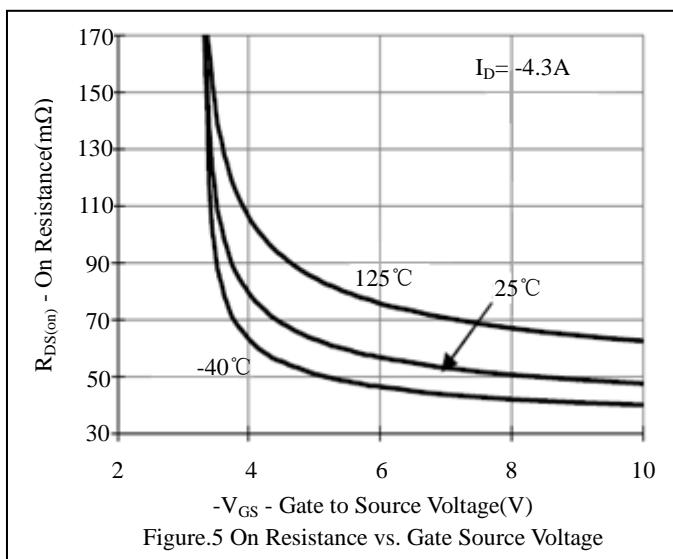


Figure.5 On Resistance vs. Gate Source Voltage

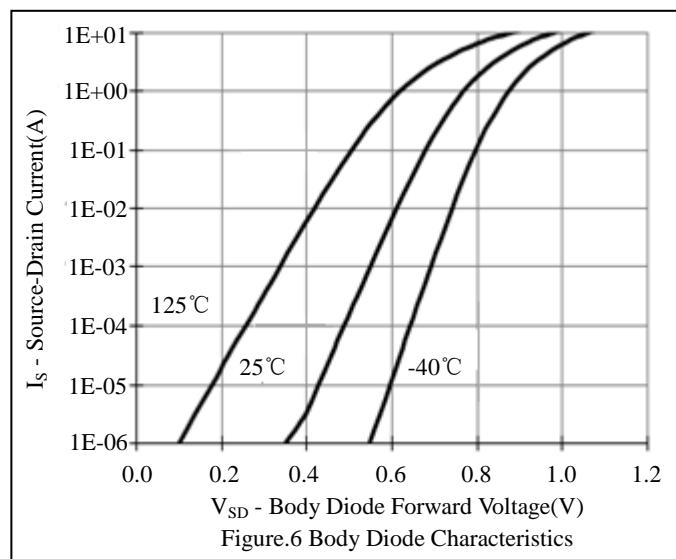


Figure.6 Body Diode Characteristics

### Characteristics Curve

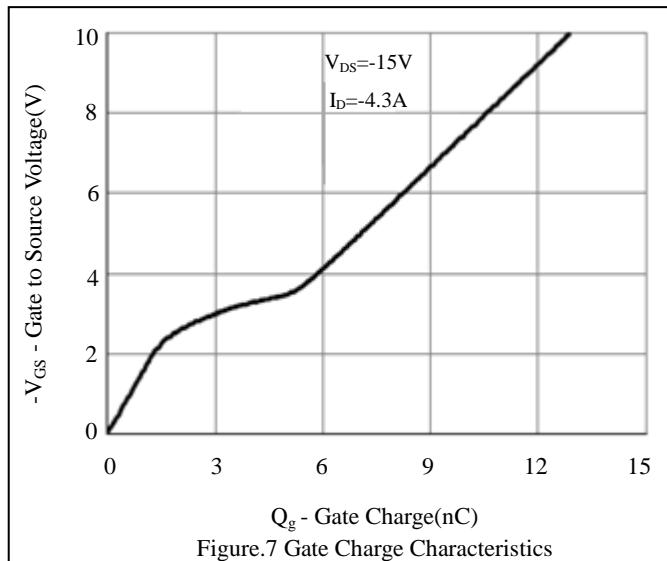


Figure.7 Gate Charge Characteristics

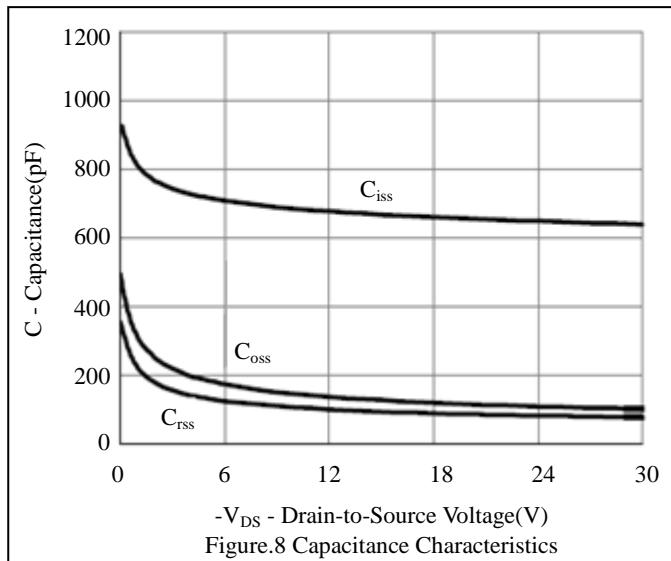


Figure.8 Capacitance Characteristics

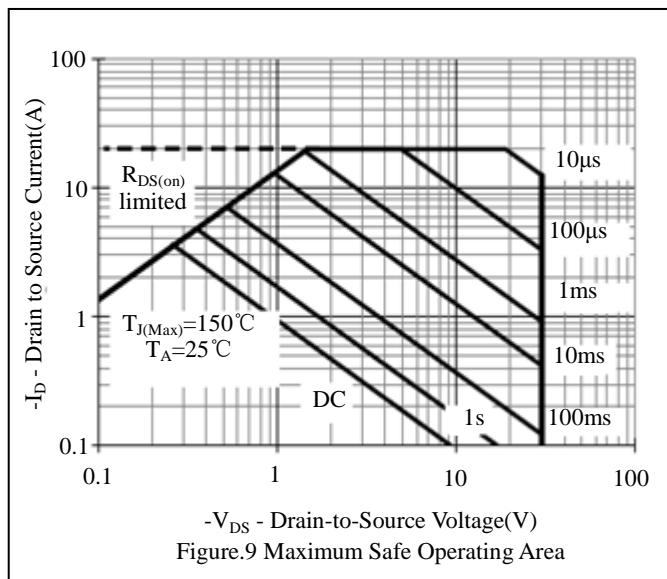


Figure.9 Maximum Safe Operating Area

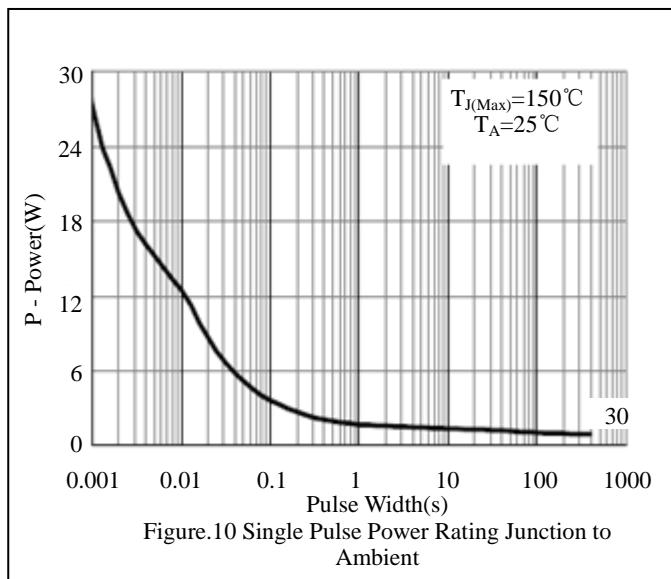


Figure.10 Single Pulse Power Rating Junction to Ambient

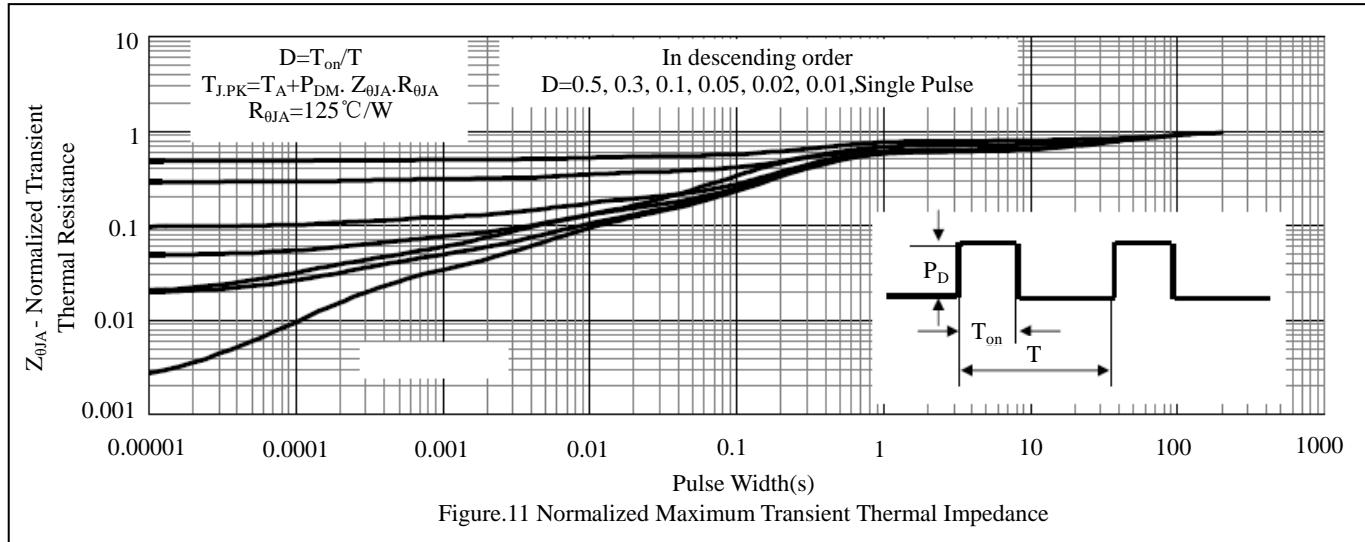
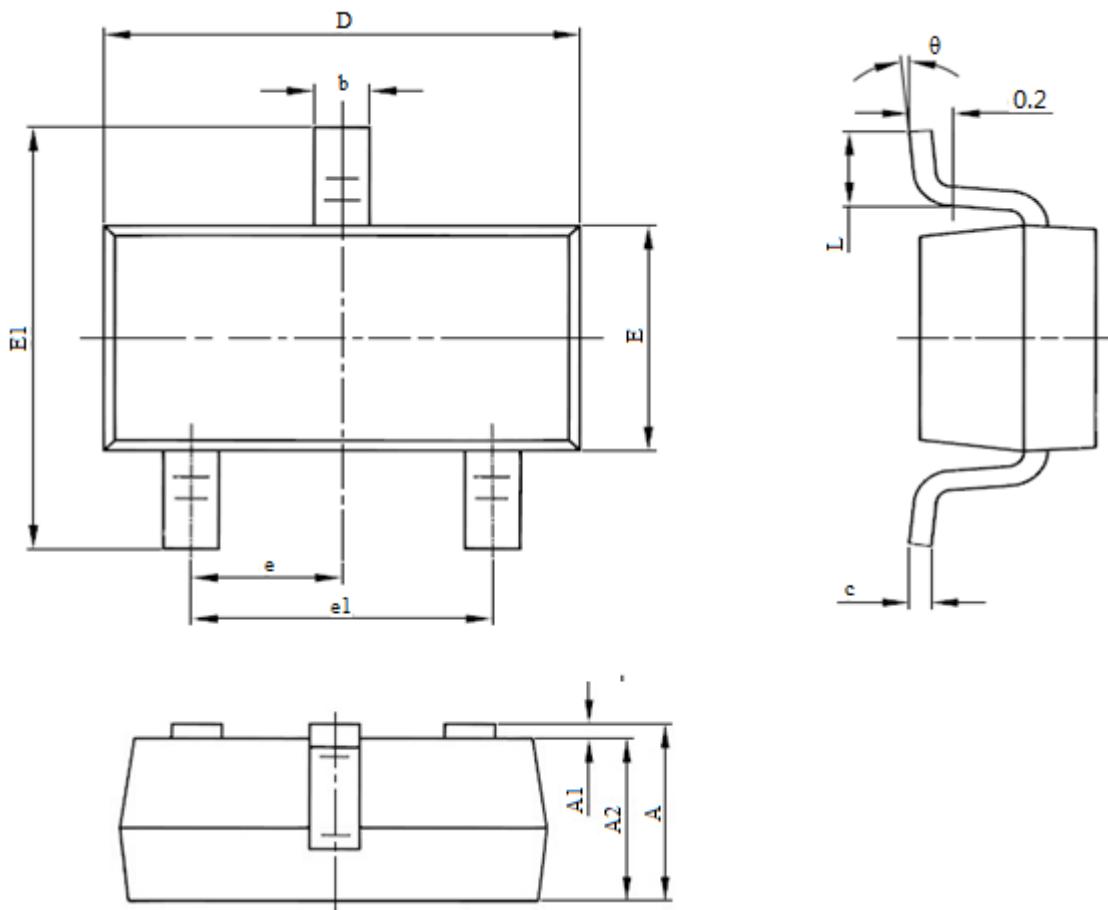


Figure.11 Normalized Maximum Transient Thermal Impedance

### SOT-23-3L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.85	1.25	0.033	0.049
A1	0	0.1	0	0.004
A2	0.7	1.15	0.028	0.045
b	0.3	0.5	0.012	0.020
c	0.1	0.2	0.004	0.008
D	2.82	3.02	0.111	0.119
E	1.5	1.7	0.059	0.067
E1	2.65	2.95	0.104	0.116
e	0.95(BSC)		0.037(BSC)	
e1	1.8	2	0.071	0.079
L	0.3	0.6	0.012	0.024
θ	0°	8°	0°	8°



### Notice

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2. Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.